

| | Hits | Search Text | DBs | Time Stamp |
|---|------|--|---|---------------------|
| 1 | 2 | "6274924".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:13 |
| 2 | 3815 | LED adj chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:13 |
| 3 | 465 | LED adj chip and lead adj frame | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:33 |
| 4 | 981 | LED adj chip same (wire wires wiring) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:15 |
| 5 | 202 | LED adj chip same (wire wires wiring) and lead adj frame | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:15 |
| 6 | 88 | LED adj chip and lead adj frame and (bent bend bending) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:17 |
| 7 | 32 | LED adj chip and lead adj frame same metal same (plated plating) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:16 |
| 8 | 51 | LED adj chip and lead adj frame and transparent adj epoxy | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:34 |
| 9 | 8 | LED adj chip and lead adj frame same metal same (plated plating) and transparent adj epoxy | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:23 |

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|----|------|---|---|---------------------|
| 10 | 19 | LED adj chip same (wire wires wiring) and lead adj frame and transparent adj epoxy | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:23 |
| 11 | 38 | LED adj chip and lead adj frame same (bent bend bending) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:30 |
| 12 | 29 | LED adj chip and lead adj frame same pattern | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:31 |
| 13 | 46 | LED adj chip and lead adj frame and "438"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:33 |
| 14 | 6 | LED adj chip and lead adj frame and transparent adj epoxy and "438"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/12/03 14:34 |
| 15 | 4 | LED adj chip and lead adj frame and plating same metal and high adj reflectivity and diode and (molding mold molded) and (lead leads) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:37 |
| 16 | 78 | LED adj chip and lead adj frame and (bent bend bending and fold folding folded) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:18 |
| 17 | 8 | LED adj chip and lead adj frame and plating same metal and high adj reflectivity and (molding mold molded) and (lead leads) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:19 |
| 18 | 4 | LED adj chip and lead adj frame and plating same metal and high adj reflectivity and (molding mold molded) and (lead leads) and electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:20 |

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| 19 | 29 | LED adj chip and lead adj frame and plating same metal and (molding mold molded) and (lead leads) and electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:20 |
| 20 | 324 | 438/26.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 21 | 177 | 438/28.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 22 | 229 | 438/33.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 23 | 307 | 438/34.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 24 | 86 | 438/35.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 25 | 2786 | 438/106.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 26 | 1041 | 438/107.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 27 | 492 | 438/112.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |

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| 28 | 825 | 438/113.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 16:22 |
| 29 | 0 | LED adj chip and lead adj frame and Ag same Au same Pd same Mi same Cr | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:38 |
| 30 | 32 | LED adj chip and lead adj frame same (Ag Au Pd Mi Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:39 |
| 31 | 33 | LED adj chip and lead adj frame same (Ag Au Pd Ni Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:41 |
| 32 | 21 | LED adj chip and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:41 |
| 33 | 36 | LED adj chip and (lead adj frame leadframe) same (Ag Au Pd Ni Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:47 |
| 34 | 258 | LED and (lead adj frame leadframe) same (Ag Au Pd Ni Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:47 |
| 35 | 156 | LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:47 |
| 36 | 104 | LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:47 |

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| 37 | 53 | LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode and (bent bend bening fold folded folding) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:48 |
| 38 | 57 | LED and (lead adj frame leadframe) with (Ag Au Pd Ni Cr) and electrode and (bent bend bending fold folded folding) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2005/01/07 18:48 |